

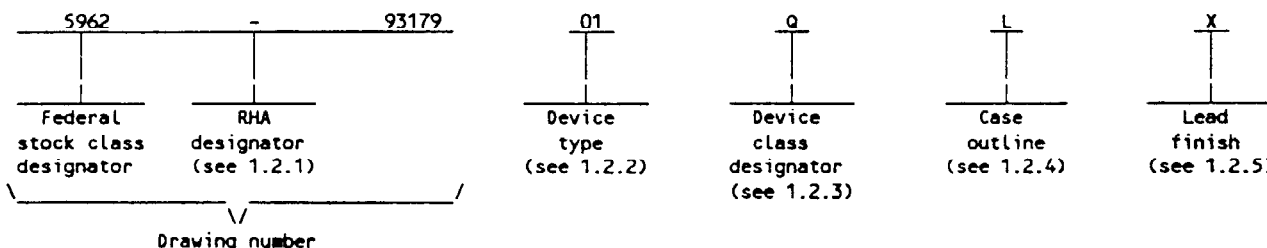
NOTICE OF REVISION (NOR)		1. DATE (YYMMDD) 94-06-01	Form Approved OMB No. 0704-0188
This revision described below has been authorized for the document listed.			
Public reporting burden for this collection is estimated to average 2 hours per response, including the time for reviewing instructions, searching existing data sources, gathering and maintaining the data needed, and completing and reviewing the collection of information. Send comments regarding this burden estimate or any other aspect of this collection of information, including suggestions for reducing this burden, to Department of Defense, Washington Headquarters Services, Directorate for Information Operations and Reports, 1215 Jefferson Davis Highway, Suite 1204, Arlington, VA 22202-4302, and to the Office of Management and Budget, Paperwork Reduction Project (0704-0188), Washington, DC 20503. PLEASE DO NOT RETURN YOUR COMPLETED FORM TO EITHER OF THESE ADDRESSED. RETURN COMPLETED FORM TO THE GOVERNMENT ISSUING CONTRACTING OFFICER FOR THE CONTRACT/ PROCURING ACTIVITY NUMBER LISTED IN ITEM 2 OF THIS FORM.			2. PROCURING ACTIVITY NO.
			3. DODAAC
4. ORIGINATOR	b. ADDRESS (Street, City, State, Zip Code) Defense Electronics Supply Center 1507 Wilmington Pike Dayton, OH 45444-5270	5. CAGE CODE 67268	6. NOR NO. 5962-R195-94
a. TYPED NAME (First, Middle Initial, Last)		7. CAGE CODE 67268	8. DOCUMENT NO. 5962-93179
9. TITLE OF DOCUMENT Microcircuit, Linear, A/D Converter, 12-Bit, CMOS, Monolithic Silicon.		10. REVISION LETTER	
		a. CURRENT	b. NEW A
11. ECP NO. No registered users			
12. CONFIGURATION ITEM (OR SYSTEM) TO WHICH ECP APPLIES			
13. DESCRIPTION OF REVISION			
<p>Sheet 1: Revisions ltr column; add "A". Revisions description column; add "Changes in accordance with NOR 5962-R195-94". Revisions date column; add "94-06-01". Revision level block; add "A". Rev status of sheets; For sheets 1 and 5, add "A".</p> <p>Sheet 5: Table I, REF<sub>OUT</sub> voltage load sensitivity, delta/V<sub>REF</sub> delta I test; Change test condition from "Reference load current change = 0 to 500 μA" to "Reference load current change = 0 to 50 μA". Revision level block; add "A".</p>			
14. THIS SECTION FOR GOVERNMENT USE ONLY			
a. (X one)	<input checked="" type="checkbox"/>	(1) Existing document supplemented by the NOR may be used in manufacture.	
	<input type="checkbox"/>	(2) Revised document must be received before manufacturer may incorporate this change.	
	<input type="checkbox"/>	(3) Custodian of master document shall make above revision and furnish revised document.	
b. ACTIVITY AUTHORIZED TO APPROVE CHANGE FOR GOVERNMENT DESC-ELDS		c. TYPED NAME (First, Middle Initial, Last) Michael A. Frye	
d. TITLE Chief, Microelectronics Branch	e. SIGNATURE Michael A. Frye		f. DATE SIGNED (YYMMDD) 94-06-01
15a. ACTIVITY ACCOMPLISHING REVISION DESC-ELDS	b. REVISION COMPLETED (Signature) Sandra Rooney		c. DATE SIGNED (YYMMDD) 94-06-01



1. SCOPE

1.1 Scope. This drawing forms a part of a one part - one part number documentation system (see 6.6 herein). Two product assurance classes consisting of military high reliability (device classes Q and M) and space application (device class V), and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). Device class M microcircuits represent non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices". When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 PIN. The PIN shall be as shown in the following example:



1.2.1 RHA designator. Device class M RHA marked devices shall meet the MIL-I-38535 appendix A specified RHA levels and shall be marked with the appropriate RHA designator. Device classes Q and V RHA marked devices shall meet the MIL-I-38535 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) shall identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	AD7876TQ	12-bit A/D converter with track/hold

1.2.3 Device class designator. The device class designator shall be a single letter identifying the product assurance level as follows:

<u>Device class</u>	<u>Device requirements documentation</u>
M	Vendor self-certification to the requirements for non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883
Q or V	Certification and qualification to MIL-I-38535

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
L	GDIP3-T24 or CDIP4-T24	24	dual-in-line

1.2.5 Lead finish. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein) for class M or MIL-I-38535 for classes Q and V. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 2

1.3 Absolute maximum ratings. 1/

V <sub>DD</sub> to AGND . . . . .	-0.3 V dc to +7.0 V dc
V <sub>SS</sub> to AGND . . . . .	+0.3 V dc to -7.0 V dc
AGND to DGND . . . . .	-0.3 V dc to V <sub>DD</sub> + 0.3 V dc
V <sub>IN</sub> to AGND . . . . .	-15 V dc to +15 V dc
REF <sub>OUT</sub> to AGND . . . . .	0 V dc to V <sub>DD</sub>
Digital inputs to DGND . . . . .	-0.3 V dc to V <sub>DD</sub> + 0.3 V dc
Digital outputs to DGND . . . . .	-0.3 V dc to V <sub>DD</sub> + 0.3 V dc
Power dissipation at T <sub>A</sub> = +75°C (P <sub>D</sub> ) 2/ . . . . .	450 mW
Lead temperature (soldering, 10 seconds) . . . . .	+300°C
Storage temperature range . . . . .	-65°C to +150°C
Thermal resistance, junction-to-case (θ <sub>JC</sub> ) . . . . .	See MIL-STD-1835

1.4 Recommended operating conditions.

Positive supply voltage (V <sub>DD</sub> ) . . . . .	+4.75 V dc to +5.25 V dc
Negative supply voltage (V <sub>SS</sub> ) . . . . .	-4.75 V dc to -5.25 V dc
AGND . . . . .	0 V dc
DGND . . . . .	0 V dc
External clock frequency (f <sub>CLK</sub> ) . . . . .	2.5 MHz
Ambient operating temperature range (T <sub>A</sub> ) . . . . .	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, bulletin, and handbook. Unless otherwise specified, the following specification, standards, bulletin, and handbook of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-I-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

MILITARY

- MIL-STD-883 - Test Methods and Procedures for Microelectronics.
- MIL-STD-973 - Configuration Management.
- MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

HANDBOOK

MILITARY

MIL-HDBK-780 - Standardized Military Drawings.

(Copies of the specification, standards, bulletin, and handbook required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.  
 2/ Derate linearly at 10 mW/°C above T<sub>A</sub> = +75°C.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 3

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

### 3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device class M shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. The individual item requirements for device classes Q and V shall be in accordance with MIL-I-38535, the device manufacturer's Quality Management (QM) plan, and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V and herein.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. Marking for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein). In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103. Marking for device classes Q and V shall be in accordance with MIL-I-38535.

3.5.1 Certification/compliance mark. The compliance mark for device class M shall be a "C" as required in MIL-STD-883 (see 3.1 herein). The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-I-38535.

3.6 Certificate of compliance. For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.7.2 herein). For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.7.1 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device class M, the requirements of MIL-STD-883 (see 3.1 herein), or for device classes Q and V, the requirements of MIL-I-38535 and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required for device class M in MIL-STD-883 (see 3.1 herein) or for device classes Q and V in MIL-I-38535 shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DESC-EC of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.

3.9 Verification and review for device class M. For device class M, DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 81 (see MIL-I-38535, appendix A).

### 4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. For device class M, sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein). For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-I-38535 and the device manufacturer's QM plan.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 4

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions 1/ -55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Resolution	RES		1, 2, 3	ALL	12		Bits
Integral nonlinearity	INL		1, 2, 3	ALL		±1.0	LSB
Differential nonlinearity	DNL		1, 2, 3	ALL		±1.0	LSB
Bipolar zero error	BZE		1, 2, 3	ALL		±6.0	LSB
Full scale error	FSE	2/	1	ALL		±8.0	LSB
			2, 3			±30	
Track/hold acquisition time	T <sub>ACQ</sub>	3/	9, 10, 11	ALL		2.0	μs
Analog input voltage range	V <sub>IN</sub>		1, 2, 3	ALL		±10	V
Analog input current	I <sub>IN</sub>		1, 2, 3	ALL		±600	μA
REF <sub>OUT</sub> voltage	V <sub>REF</sub>		1	ALL	2.99	3.01	V
REF <sub>OUT</sub> voltage temperature coefficient	delta/ V <sub>REF</sub> delta T		2, 3	ALL		±60	ppm/°C
REF <sub>OUT</sub> voltage load sensitivity	delta/ V <sub>REF</sub> delta I	Reference load current 4/ change = 0 to 500 μA	1, 2, 3	ALL		-1.0	mV
Input logic high voltage	V <sub>INH</sub>	3/	1, 2, 3	ALL	2.4		V
Input logic low voltage	V <sub>INL</sub>	3/	1, 2, 3	ALL		0.8	V
Output logic high voltage	V <sub>OH</sub>	I <sub>SOURCE</sub> = 40 μA	1, 2, 3	ALL	4.0		V
Output logic low voltage	V <sub>OL</sub>	I <sub>SINK</sub> = 1.6 mA	1, 2, 3	ALL		0.4	V
Input current	I <sub>IN</sub>	V <sub>IN</sub> = 0 V to V <sub>DD</sub>	1, 2, 3	ALL		±10	μA
		12/8/CLK input only, V <sub>IN</sub> = V <sub>SS</sub> to V <sub>DD</sub>				±10	

See footnotes at end of table.

STANDARDIZED  
MILITARY DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

SIZE  
A

5962-93179

REVISION LEVEL

SHEET

5

TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions 1/ -55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Supply current	I <sub>DD</sub>		1, 2, 3	ALL		13	mA
	I <sub>SS</sub>					6.0	
Input capacitance	C <sub>IN</sub>	See 4.4.1c	4	ALL		10	pF
DB11 - DB0 floating state output capacitance	C <sub>OUT</sub>	See 4.4.1c	4	ALL		15	pF
DB11 - DB0 floating state leakage current	I <sub>L</sub>		1, 2, 3	ALL		10	μA
External clock conversion time	t <sub>CONV (ext)</sub>	f <sub>CLK</sub> = 2.5 MHz, see figure 2	9, 10, 11	ALL	7.2	8.0	μs
Internal clock conversion time	t <sub>CONV (int)</sub>	See figure 2	9, 10, 11	ALL	6.5	9.0	μs
CONVST pulse width	t <sub>1</sub>	5/ 6/	9	ALL	50		ns
CS to RD setup time (mode 1)	t <sub>2</sub>	5/ 6/	9	ALL	0		ns
RD pulse width	t <sub>3</sub>	5/	9, 10, 11	ALL	75		ns
CS to RD hold time (mode 1)	t <sub>4</sub>	5/ 6/	9	ALL	0		ns
RD to INT delay time	t <sub>5</sub>	5/ 6/	9	ALL		70	ns
Data access time after RD	t <sub>6</sub>	5/ 7/	9, 10, 11	ALL		70	ns
Bus relinquish time after RD	t <sub>7</sub>	5/ 8/	9, 10, 11	ALL	5.0	50	ns
HBEN to RD setup time	t <sub>8</sub>	5/ 6/	9	ALL	0		ns
HBEN to RD hold time	t <sub>9</sub>	5/ 6/	9	ALL	0		ns
SSTRB to SCLK falling edge setup time	t <sub>10</sub>	5/ 6/	9	ALL	100		ns

See footnotes at end of table.

STANDARDIZED  
MILITARY DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

SIZE  
A

5962-93179

REVISION LEVEL

SHEET

6

TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions 1/ -55°C ≤ T <sub>A</sub> ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
SCLK cycle time	t <sub>11</sub>	5/ 6/ 9/	9	ALL	370		ns
SCLK to valid data delay time	t <sub>12</sub>	5/ 6/ 10/	9	ALL		150	ns
SCLK rising edge to $\overline{\text{SSTRB}}$	t <sub>13</sub>	5/ 6/	9	ALL	20	100	ns
Bus relinquish time after SCLK	t <sub>14</sub>	5/ 6/	9	ALL	10	100	ns
$\overline{\text{CS}}$ to $\overline{\text{RD}}$ setup time (mode 2)	t <sub>15</sub>	5/ 6/	9	ALL	60		ns
Propagation delay time, $\overline{\text{CS}}$ to BUSY	t <sub>16</sub>	5/ 6/	9	ALL		120	ns
Data setup time prior to BUSY	t <sub>17</sub>	5/ 6/	9	ALL	200		ns
$\overline{\text{CS}}$ to $\overline{\text{RD}}$ hold time (mode 2)	t <sub>18</sub>	5/ 6/	9	ALL	0		ns
HBEN to $\overline{\text{CS}}$ setup time	t <sub>19</sub>	5/ 6/	9	ALL	0		ns
HBEN to $\overline{\text{CS}}$ hold time	t <sub>20</sub>	5/ 6/	9	ALL	0		ns

1/ V<sub>DD</sub> = +4.75 V to +5.25 V, V<sub>SS</sub> = -4.75 V to -5.25 V, AGND = DGND = 0 V, f<sub>CLK</sub> = 2.5 MHz external.

2/ Includes internal reference error and is calculated after bipolar zero error has been adjusted out.

3/ Guaranteed by dc accuracy test results when used as a setup condition.

4/ Reference load should not be changed during conversion.

5/ Input t<sub>r</sub>, t<sub>f</sub> = 5.0 ns (10% to 90% of +5.0 V), timing voltage reference level = 1.6 V, see figure 2.

6/ Guaranteed if not tested.

7/ Test t<sub>6</sub> is defined as the time required for an output to cross 0.8 V or 2.4 V.

8/ Test t<sub>7</sub> is defined as the time required for the data lines to change 0.5 V.

9/ SCLK mark/space ratio (measured from a voltage level of 1.6 V) is 40/60 to 60/40.

10/ SDATA will drive higher capacitive loads but will add to t<sub>12</sub> since it increases the external RC time constant (4.7kΩ || C<sub>L</sub>) and hence the time to reach 2.4 V, C<sub>L</sub> = 35 pF.

STANDARDIZED  
MILITARY DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

SIZE  
A

5962-93179

REVISION LEVEL

SHEET

7



Device type	01
Case outline	L
Terminal number	Terminal symbol
1	$\overline{RD}$
2	$\overline{BUSY/INT}$
3	CLK
4	DB11/ $\overline{HBEN}$
5	DB10/ $\overline{SSTRB}$
6	DB9/SCLK
7	DB8/SDATA
8	DB7/LOW
9	DB6/LOW
10	DB5/LOW
11	DB4/LOW
12	DGND
13	DB3/DB11
14	DB2/DB10
15	DB1/DB9
16	DB0/DB8
17	V <sub>DD</sub>
18	AGND
19	REF <sub>OUT</sub>
20	V <sub>IN</sub>
21	V <sub>SS</sub>
22	12/ $\overline{8}$ /CLK
23	$\overline{CONVST}$
24	$\overline{CS}$

FIGURE 1. Terminal connections.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 8

Mode 1, 12-bit parallel read.

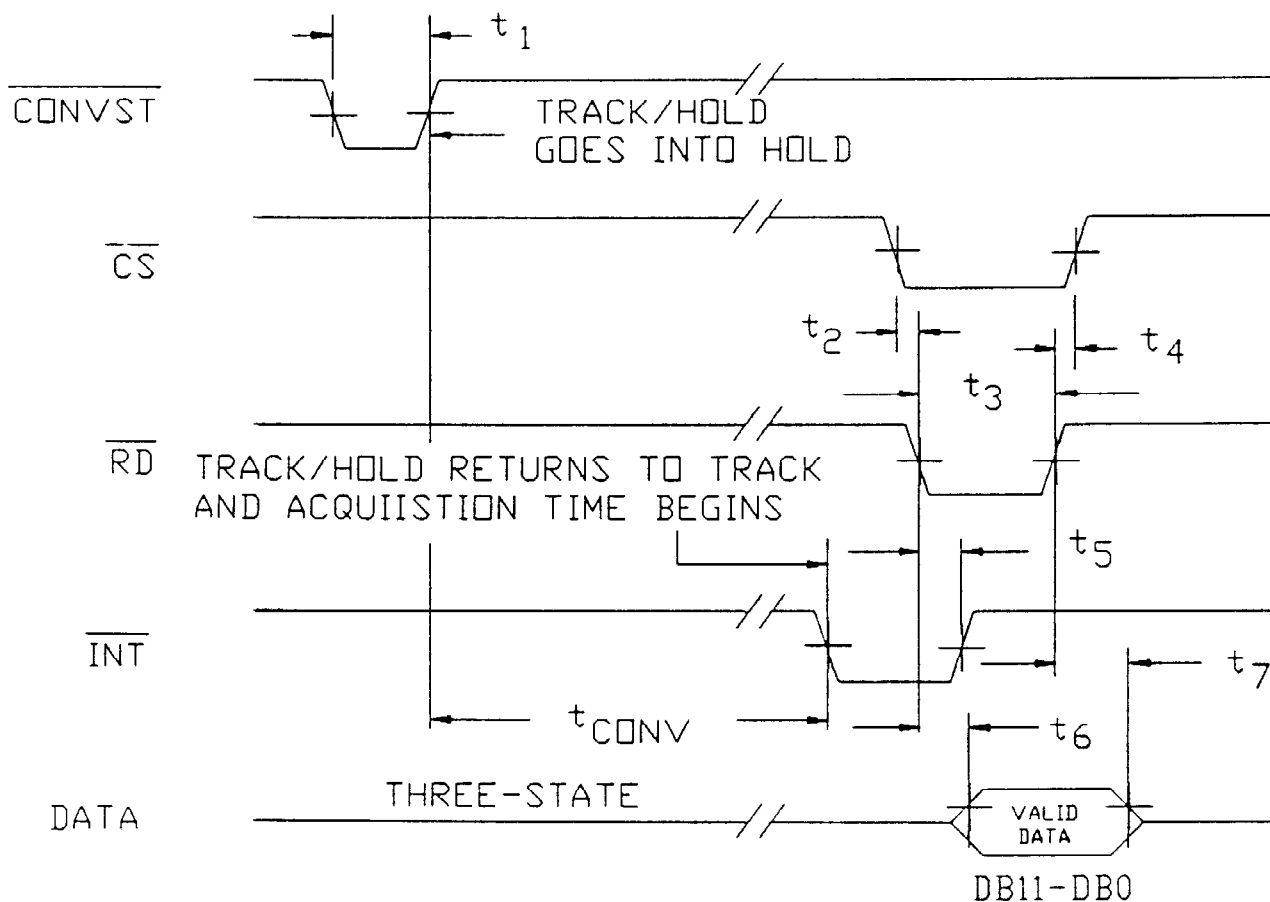
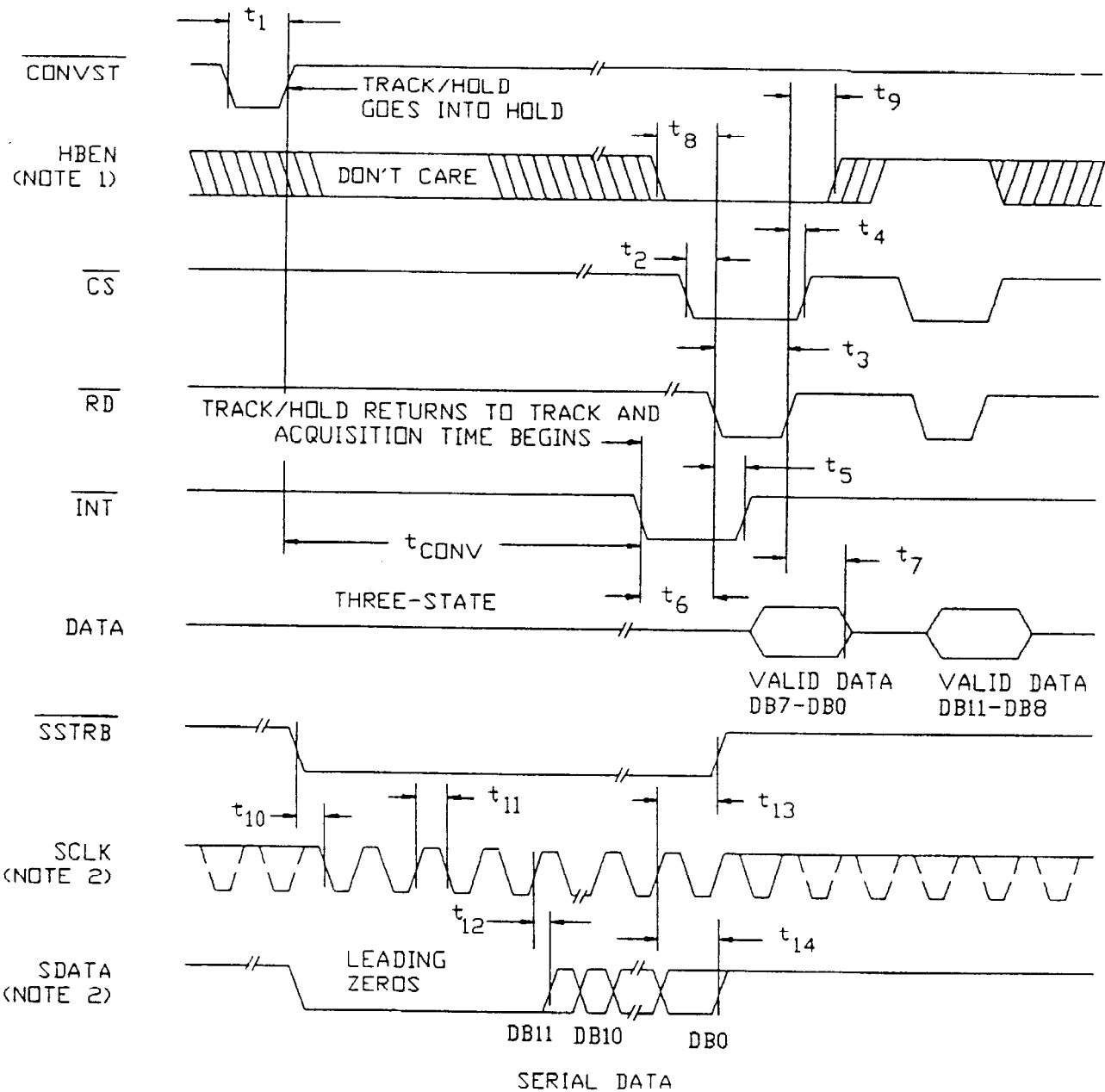


FIGURE 2. Timing waveforms.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE <b>A</b>		5962-93179
		REVISION LEVEL	SHEET 9

Mode 1, byte or serial read.



Notes:

1. Times  $t_2$ ,  $t_3$ ,  $t_4$ ,  $t_8$ , and  $t_9$  are the same for a high byte read as for a low byte read.
2. External  $2\text{k}\Omega$  pull-up resistor.
3. External  $2\text{k}\Omega$  pull-up resistor, continuous SCLK (dashed line) when  $12/\bar{8}/\text{CLK} = -5.0 \text{ V}$ , noncontinuous when  $12/\bar{8}/\text{CLK} = 0 \text{ V}$ .

FIGURE 2. Timing waveforms - continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 10

Mode 2, 12-bit parallel read.

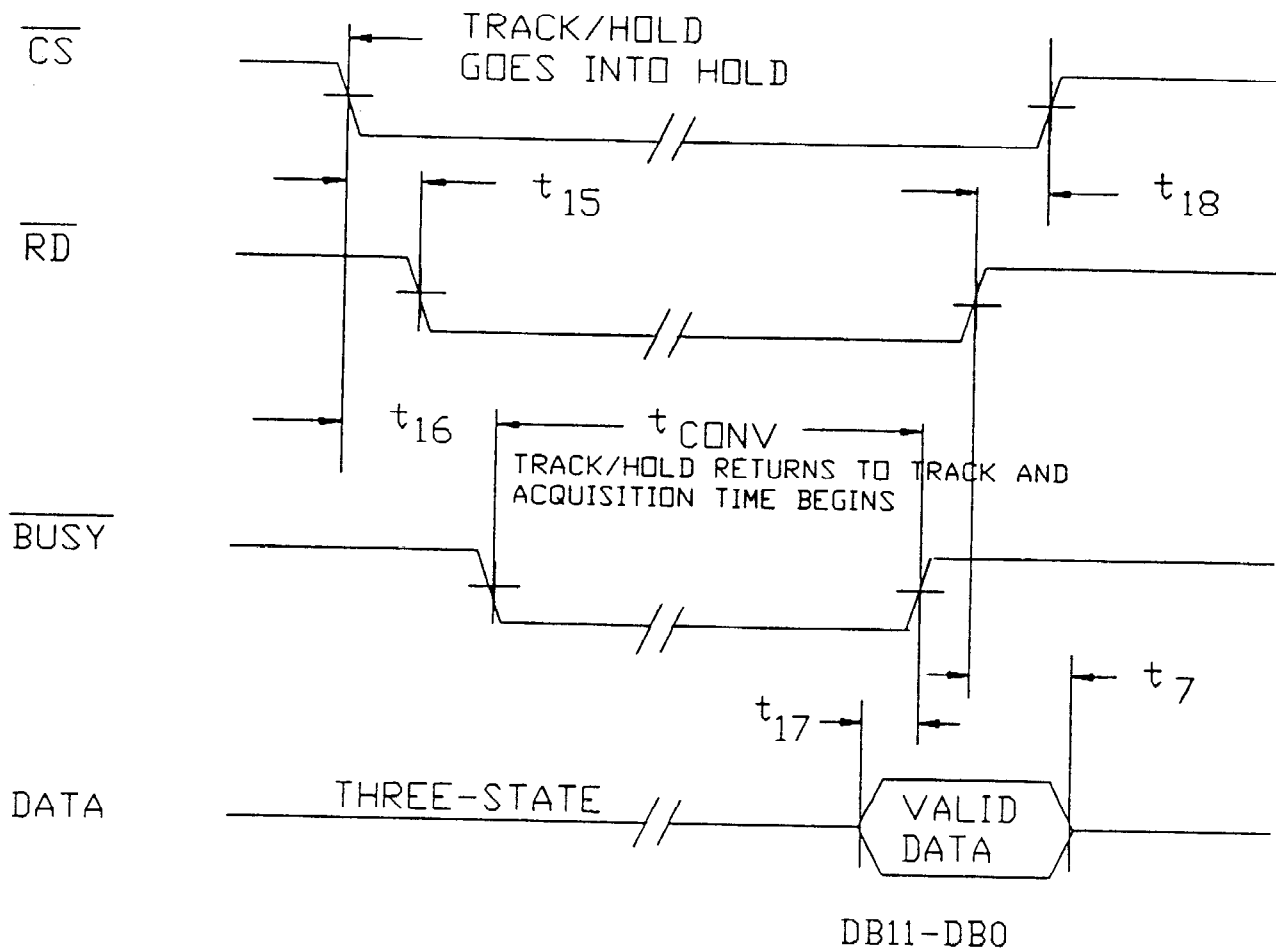
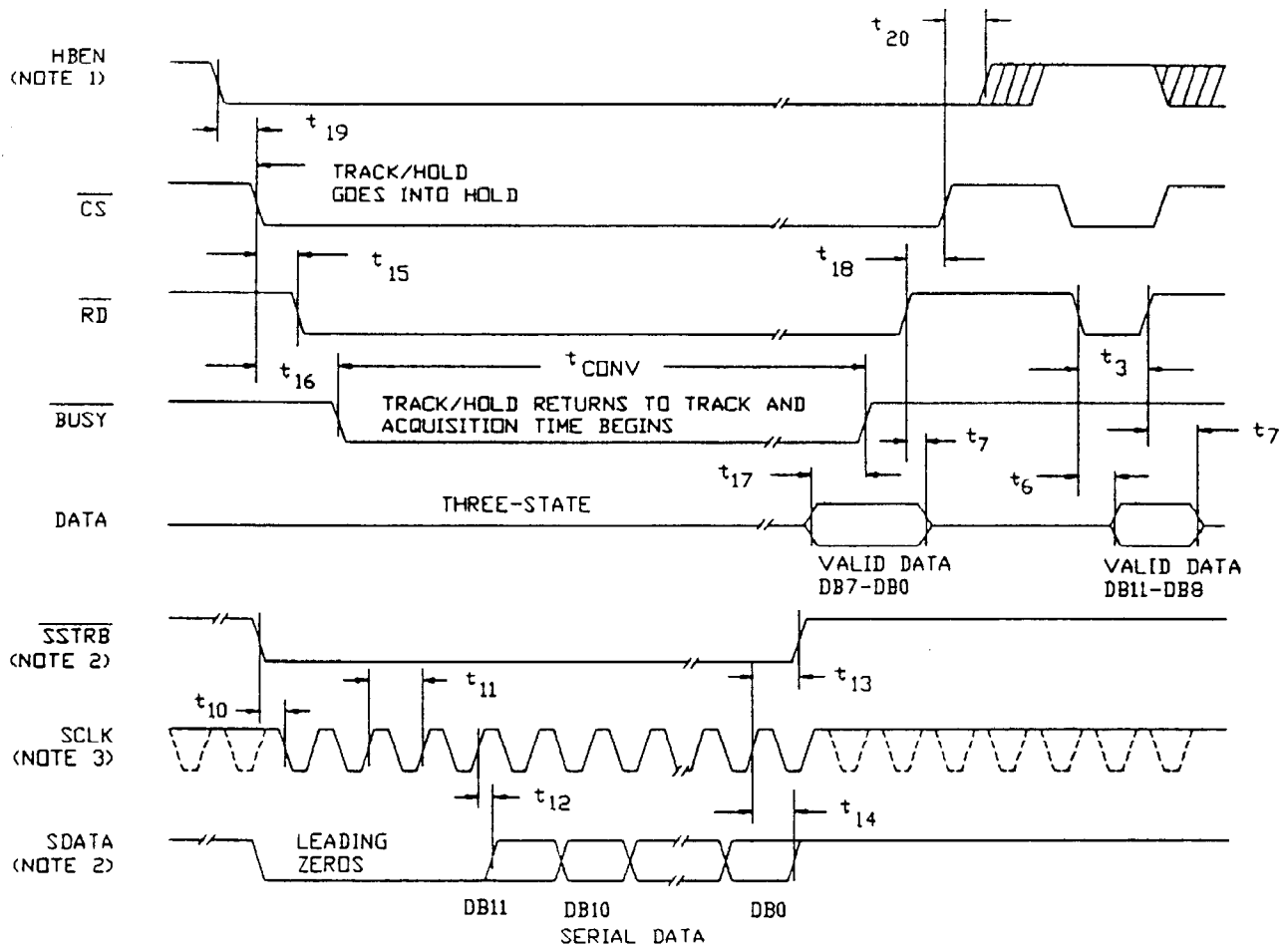


FIGURE 2. Timing waveforms - continued.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 11

Mode 2, byte or serial read.



Notes:

1. Times  $t_2$ ,  $t_3$ ,  $t_4$ ,  $t_8$ , and  $t_9$  are the same for a high byte read as for a low byte read.
2. External  $2k\Omega$  pull-up resistor.
3. External  $2k\Omega$  pull-up resistor, continuous SCLK (dashed line) when  $12\bar{8}/CLK = -5.0$  V, noncontinuous when  $12\bar{8}/CLK = 0$  V.

FIGURE 2. Timing waveforms - continued.

STANDARDIZED  
MILITARY DRAWING  
DEFENSE ELECTRONICS SUPPLY CENTER  
DAYTON, OHIO 45444

SIZE  
A

5962-93179

REVISION LEVEL

SHEET

12

4.2 Screening. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. For device classes Q and V, screening shall be in accordance with MIL-I-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.

4.2.1 Additional criteria for device class M.

- a. Burn-in test, method 1015 of MIL-STD-883.
  - (1) Test condition A, B, C, D, or E. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
  - (2)  $T_A = +125^\circ\text{C}$ , minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein.

4.2.2 Additional criteria for device classes Q and V.

- a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-I-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
- b. Interim and final electrical test parameters shall be as specified in table II herein.
- c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in appendix B of MIL-I-38535.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-I-38535. Inspections to be performed shall be those specified in MIL-I-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Quality conformance inspection for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein) and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4). Technology conformance inspection for classes Q and V shall be in accordance with MIL-I-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-I-38535 permits alternate in-line control testing.

4.4.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5, 6, 7, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 ( $C_{IN}$  and  $C_{OUT}$  measurement) shall be measured only for the initial test and after process or design changes which may affect capacitance. A minimum sample of five devices with zero rejects shall be tested.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, D, or E. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.
- b.  $T_A = +125^\circ\text{C}$ , minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 13

TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, TM 5005, table I)	Subgroups (in accordance with MIL-I-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	<u>1/</u> 1, 2, 3, 9, 10, 11	<u>1/</u> 1, 2, 3, 9, 10, 11	<u>1/</u> 1, 2, 3, 9, 10, 11
Group A test requirements (see 4.4)	1, 2, 3, 4, 9, 10, 11	1, 2, 3, 4, 9, 10, 11	1, 2, 3, 4, 9, 10, 11
Group C end-point electrical parameters (see 4.4)	1	1	1, 2, 3, 4, 9, 10, 11
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)	---	---	---

1/ PDA applies to subgroup 1.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB, in accordance with MIL-I-38535, and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes Q and V shall be M, D, R, and H and for device class M shall be M and D.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-I-38535, appendix A, for the RHA level being tested. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-I-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at  $T_A = +25^\circ\text{C} \pm 5^\circ\text{C}$ , after exposure, to the subgroups specified in table II herein.
- c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 14

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and which SMD's are applicable to that system. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.

6.4 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-I-38535 and MIL-STD-1331.

6.6 One part - one part number system. The one part - one part number system described below has been developed to allow for transitions between identical generic devices covered by the three major microcircuit requirements documents (MIL-H-38534, MIL-I-38535, and 1.2.1 of MIL-STD-883) without the necessity for the generation of unique PIN's. The three military requirements documents represent different class levels, and previously when a device manufacturer upgraded military product from one class level to another, the benefits of the upgraded product were unavailable to the Original Equipment Manufacturer (OEM), that was contractually locked into the original unique PIN. By establishing a one part number system covering all three documents, the OEM can acquire to the highest class level available for a given generic device to meet system needs without modifying the original contract parts selection criteria.

<u>Military documentation format</u>	<u>Example PIN under new system</u>	<u>Manufacturing source listing</u>	<u>Document listing</u>
New MIL-H-38534 Standardized Military Drawings	5962-XXXXXZZ(H or K)YY	QML-38534	MIL-BUL-103
New MIL-I-38535 Standardized Military Drawings	5962-XXXXXZZ(Q or V)YY	QML-38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standardized Military Drawings	5962-XXXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

6.7 Sources of supply.

6.7.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DESC-EC and have agreed to this drawing.

6.7.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-93179
		REVISION LEVEL	SHEET 15



STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN

DATE: 94-02-17

Approved sources of supply for SMD 5962-93179 are listed below for immediate acquisition only and shall be added to MIL-BUL-103 during the next revision. MIL-BUL-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-EC. This bulletin is superseded by the next dated revision of MIL-BUL-103.

Standardized military drawing PIN	Vendor CAGE number	Vendor similar PIN <sup>1/</sup>
5962-9317901MLX	24355	AD7876TQ/883B

<sup>1/</sup> Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number

24355

Vendor name and address

Analog Devices  
181 Ballardvale Street  
Wilmington, MA 01887-1024

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.